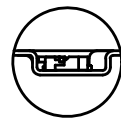
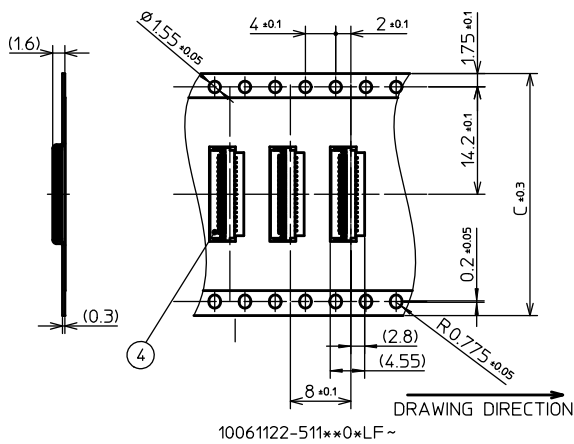
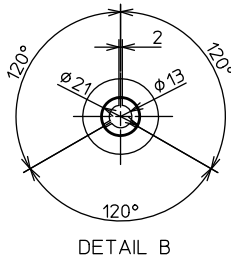
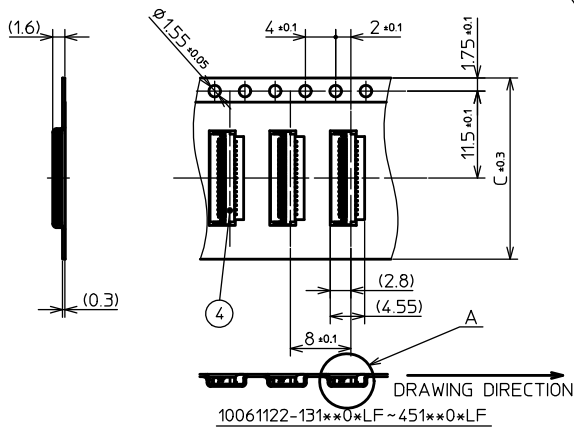
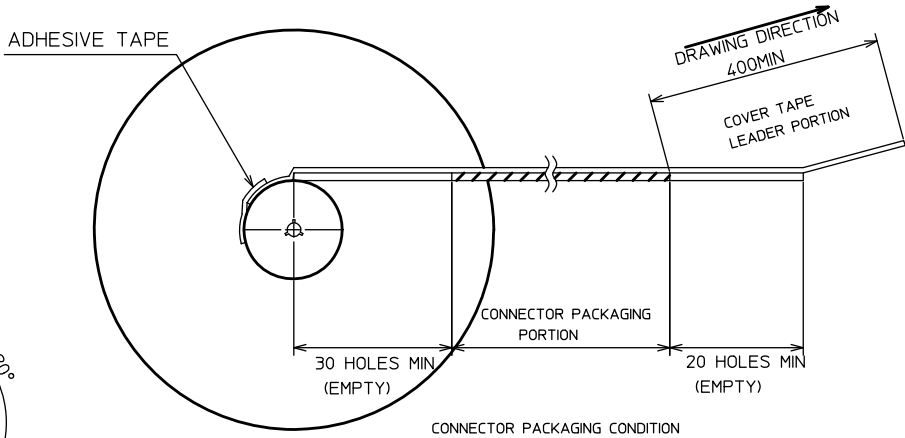
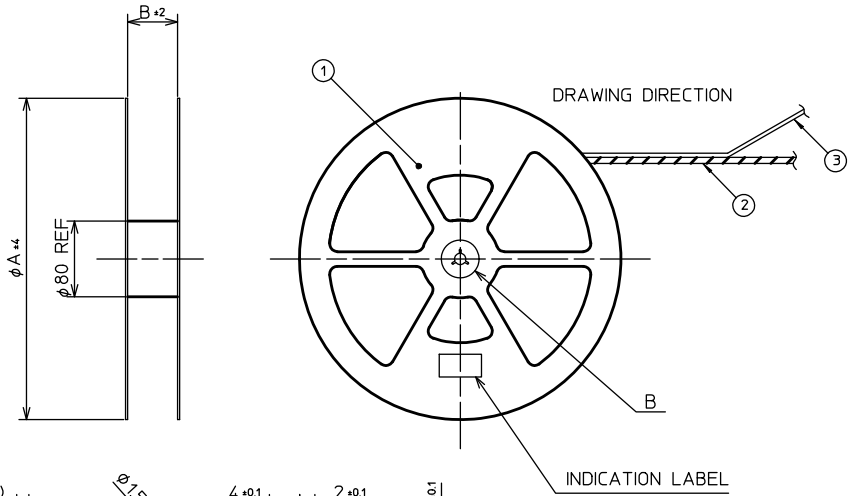


PRODUCT NO
10061122-**-1**0*LF

EMBOSS TAPE	DIMENSIONS		
	φ A	B	C
10061122-131**0*LF~451**0*LF	φ330	25.5	24
10061122-511**0*LF~		33.5	32

PT.NO.	PARTS NAME	PRODUCT NO.	MATERIAL	Q'TY	NOTE
1	REEL		POLYSTYRENE	1	COLOR:WHITE.ELECTRIFICATION PREVENTION PROCESSING
2	EMBOSS TAPE		PP OR PET	1	ELECTRIFICATION PREVENTION PROCESSING
3	COVER TAPE		POLYESTER		
4	CONNECTOR	10061122-**-1**0*LF	10061122 SHEET2,3	5000	
		10061122-**-1**HLF	10061122 SHEET4,5 6,7		



Actuator is close
Initial condition

DETAIL A

- NOTE
- THIS ARTICLE CARRIES OUT THE EMBOSS TAPE PACKAGE OF THE P/N10061122 SERIES CONNECTOR
 - THE SHAPE AND DIMENSION OF THIS ARTICLE ARE BASED ON JIS C 0806 (TAPING OF ELECTRONIC PARTS(SURFACE MOUNTED DEVICE))

P/N COMPOSITION
10061122-**-1**0*LF

HOUSING MATERIAL 1: NONE-HALOGEN FREE RESIN
2: HALOGEN FREE RESIN

LEAD FREE

PACKAGING FORM (E PLASTIC REEL/EMBOSS TAPE PACKAGE)

EMBOSSING TAPE PACKAGE 0: 8mm PITCH

PLATING SPEC 1: AU PLATING

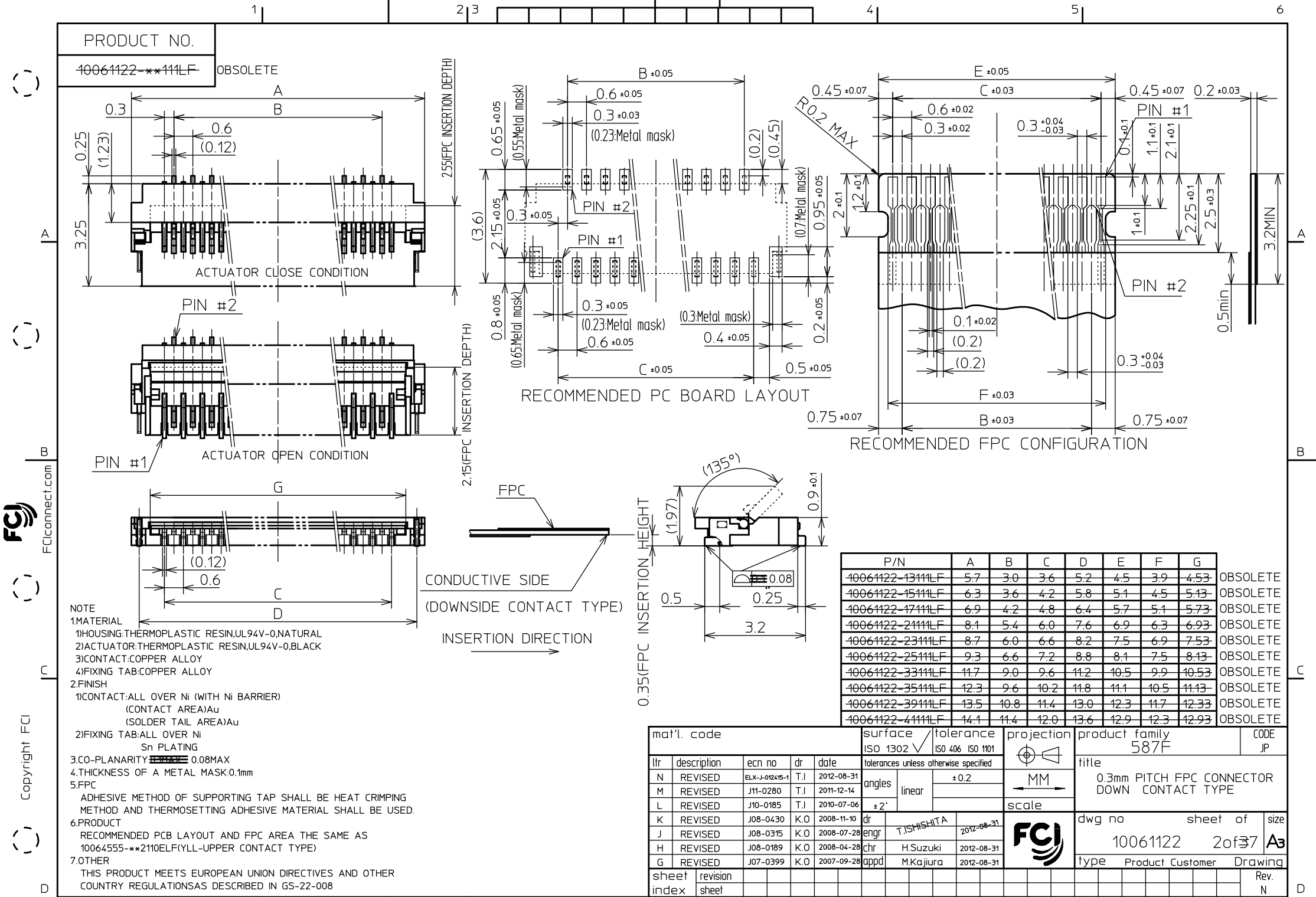
MOUNTING 1: SMT/WITH CABLE LOCK
2: SMT/WITHOUT CABLE LOCK
3: SMT/WITH CABLE LOCK/WITH ACTUATOR LOCK
4: SMT/WITHOUT CABLE LOCK/WITH ACTUATOR LOCK

CONTACT SIDE 1: DOWN SIDE

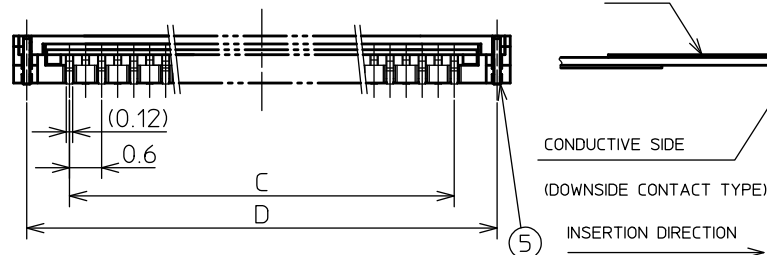
NO OF POSITION

SERIES NAME

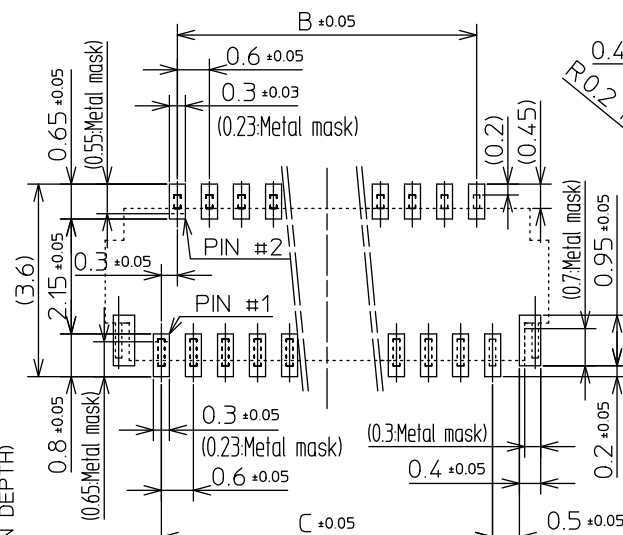
mat'l. code					surface  tolerance		projection 		product family		CODE	
					ISO 1302		ISO 406 ISO 101		587F (YLL-D)		JP	
					tolerances unless otherwise specified				title			
ltr	description	ecn no	dr	date	angles	linear	± 0.3		0.3mm PITCH FPC CONNECTOR			
T	REVISED	ELX-J-20618	TJ	2015-04-17					DOWN CONTACT TYPE ET PACKAGING			
S	REVISED	ELX-J-14161	TJ	2013-03-05								
R	REVISED	ELX-J-0245	TJ	2012-08-31	± 3		scale					
P	REVISED	J11-0280	TJ	2011-12-14	dr	T.Ishihita	2015-04-17		dwg no		sheet of	size
N	REVISED	J10-0268	TJ	2010-10-12	engr	M.Minato	2015-04-17		10061122		10F37	A2
M	REVISED	J10-0185	TJ	2010-07-06	chr	N.Sasame	2015-04-17		type		Product	Customer
L	REVISED	J10-0073	TJ	2010-05-17	appd	N.Sasame	2015-04-17		Drawing			Rev.
sheet	revision	T	N	G	A	C	C					
index	sheet	1	2	3	4	5	6	7				



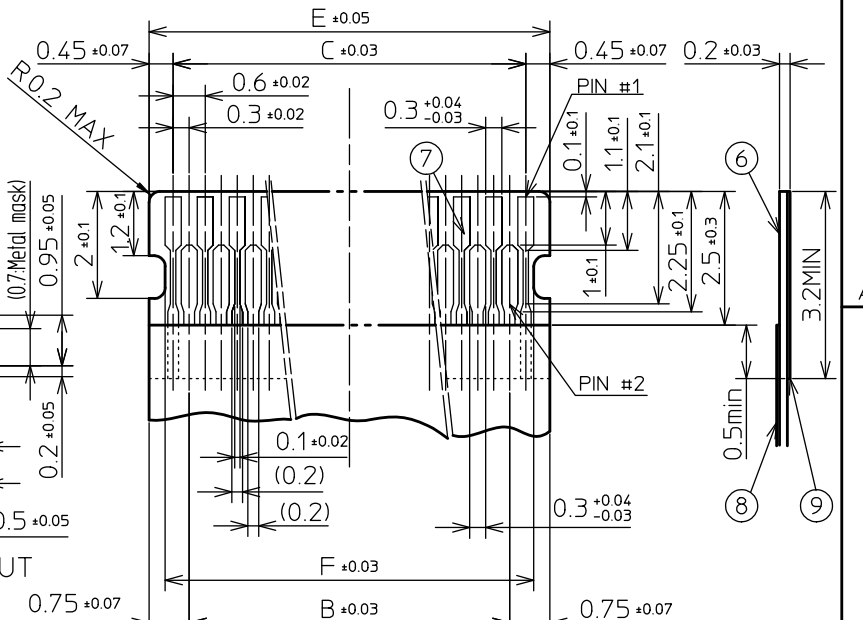
Printed: Apr 20, 2015



NOTE	nNO OF CONTACT
1.CO-PLANARITY:0.08mmMAX	
2.THICKNESS OF A METAL MASK:0.1mm	
3.FPC	
Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.	
4.PRODUCT	
Recommended PCB layout and FPC area the same as 10064555-**2110*LF(YLL-Upper contact type)	
5.OTHER	
This product meets European Union Directives and other country regulation as described in GS-22-008	



RECOMMENDED PC BOARD LAYOUT



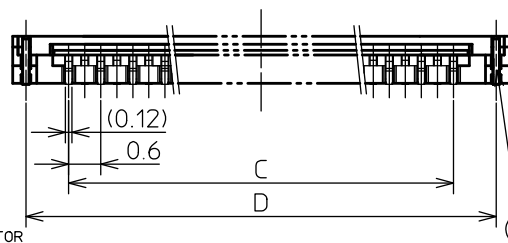
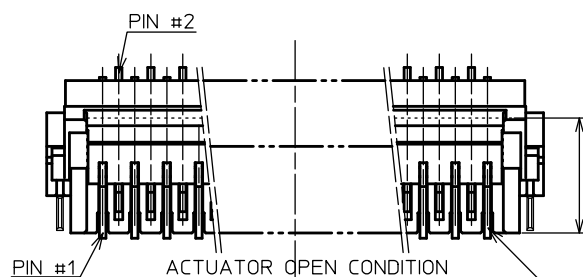
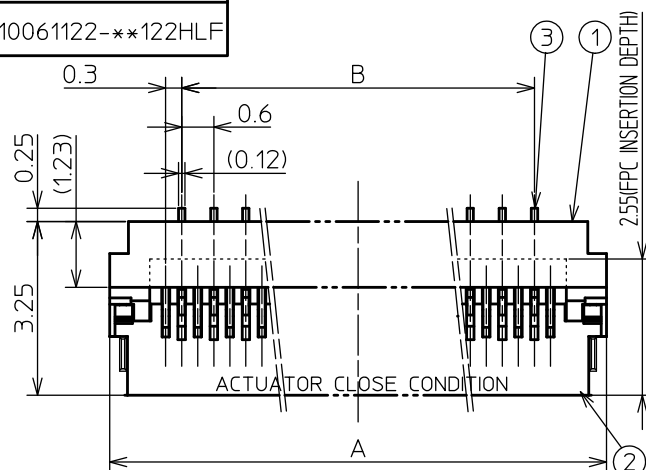
RECOMMENDED FPC CONFIGURATION

n: NO OF CONTACT

P/N	A	B	C	D	E	F
10061122-13112HLF	5.7	3.0	3.6	5.2	4.5	3.9
10061122-15112HLF	6.3	3.6	4.2	5.8	5.1	4.5
10061122-17112HLF	6.9	4.2	4.8	6.4	5.7	5.1
10061122-21112HLF	8.1	5.4	6.0	7.6	6.9	6.3
10061122-23112HLF	8.7	6.0	6.6	8.2	7.5	6.9
10061122-25112HLF	9.3	6.6	7.2	8.8	8.1	7.5

*For the corresponding position, please make an inquire to sales person in our company.

mat'l. code					surface ISO 1302		tolerance ISO 406 ISO 1101		projection 		product family 587F (YLL-D)			CODE JP	
ltr		description		ecn no	dr	date		tolerances unless otherwise specified				title			
A		Released		J10-0185	T.I	2010-07-06		angles		linear		±0.2		 0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE	
								±2'				scale			
								dr		T.ISHISHITA		2010-07-06			
								enrg		Y.Kameda		2010-07-06			
								chr		M.Kajiura		2010-07-06			
								appd						dwg no sheet of size 10061122 4 of 7 A3	
sheet index		revision sheet												type Product Customer Drawing A	

CONNECTOR

	PARTS NAME	MATERIAL	QTY	REMARKS
1	HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2	ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3	CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni WITH Ni BARRIER
4	CONTACT B	COPPER ALLOY	(n+1)/2	CONTACT AREA SOLDER TAIL AREA: Au
5	FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni, Sn

NOTE

1.CO-PLANARITY:0.08mmMAX

2. THICKNESS OF A METAL MASK: 0.1mm

3.FPC

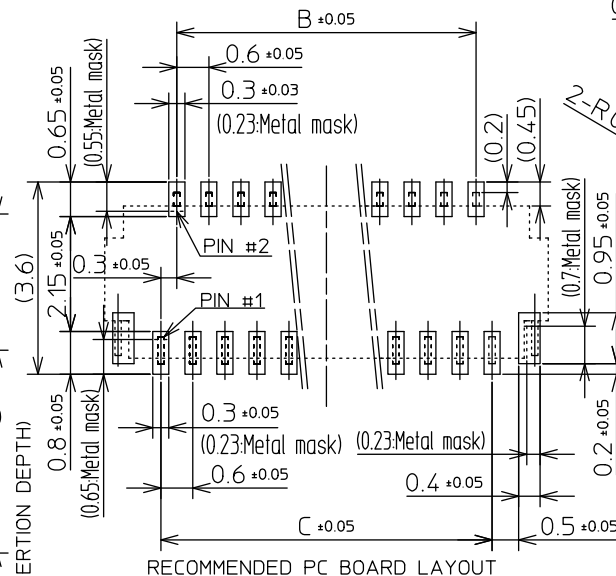
Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.

4.PRODUCT

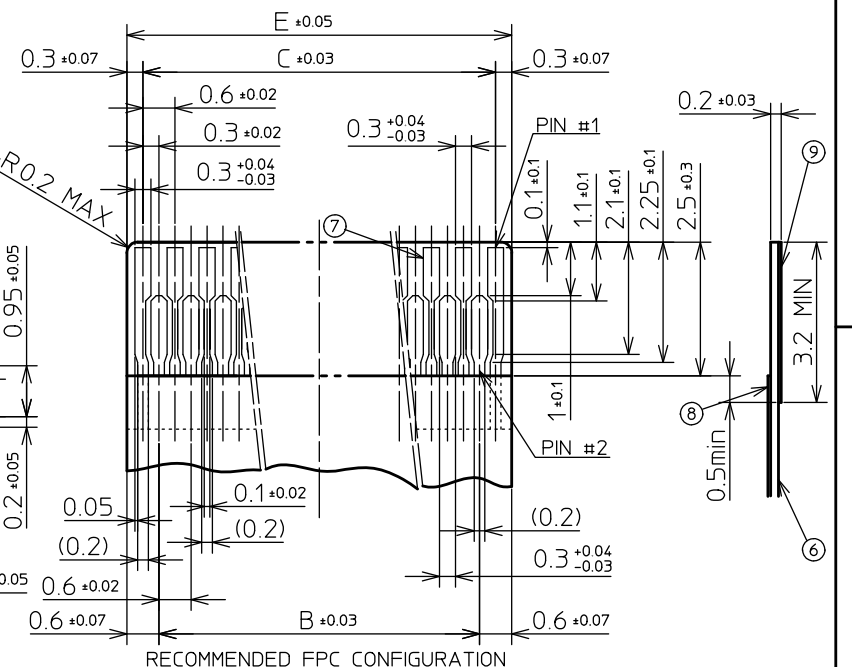
Recommended PCB layout and FPC area the same as 10064555-**2110*LF(YLL-Upper contact type)

5. OTHER

This product meets European Union Directives and other country regulation as described in GS-22-008



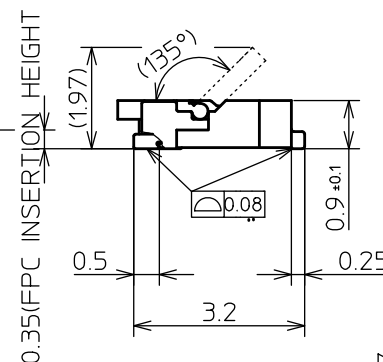
RECOMMENDED PC BOARD LAYOUT



RECOMMENDED FPC CONFIGURATION

FPC				
	PARTS NAME	MATERIAL	QTY	REMARKS
6	BASE FILM	POLYAMDE	1	
7	CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4-12 μ Au 0.05-0.15 μ m
8	OVERLAY	POLYAMIDE	1	
9	STIFFENER	POLYAMIDE	1	

n: NO OF CONTACT



0.35(FPC INSERTION HEIGHT)

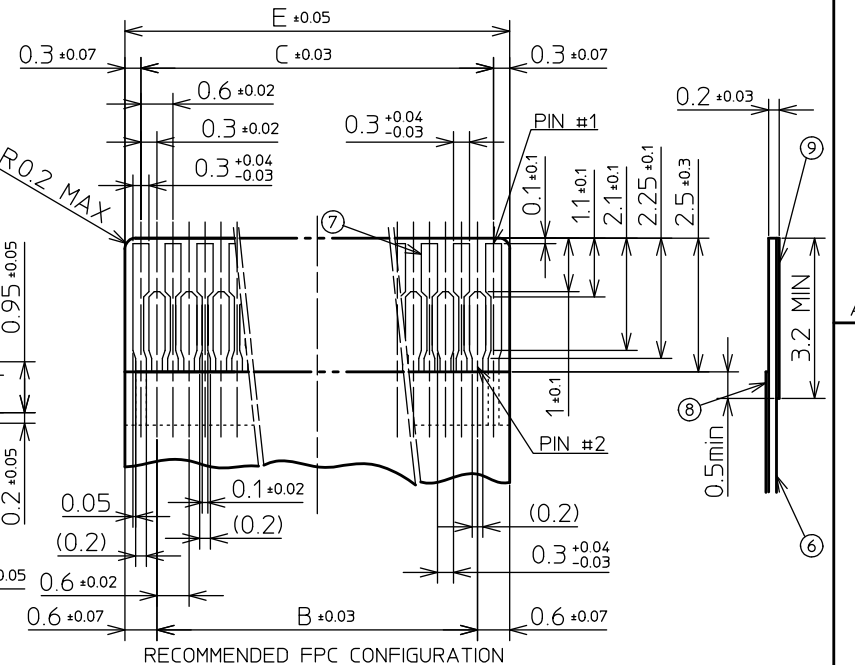
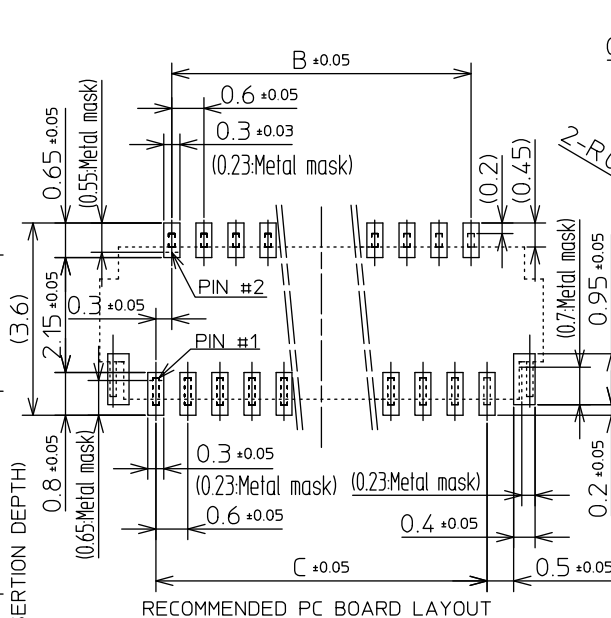
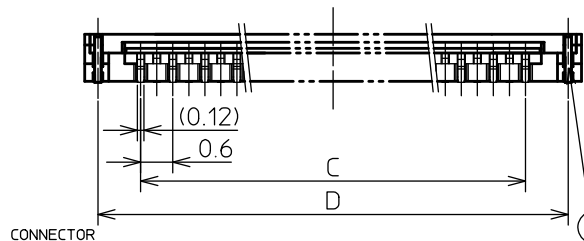
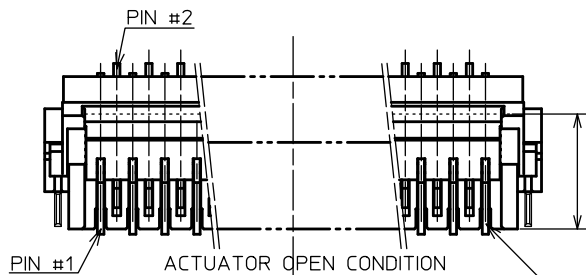
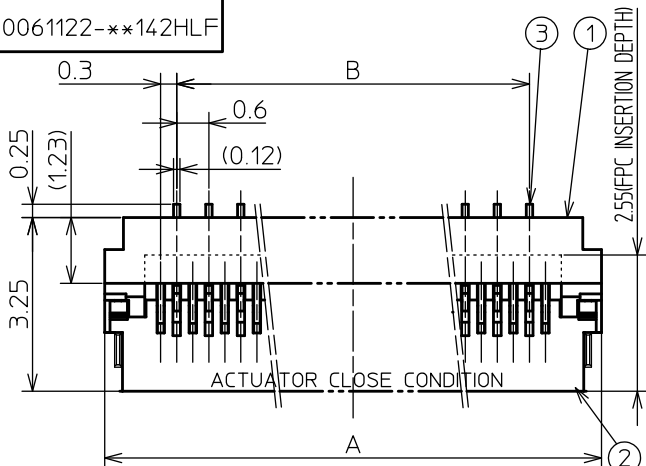
P/N	A	B	C	D	E
10061122-15122HLF	6.3	3.6	4.2	5.8	4.8
10061122-21122HLF	8.1	5.4	6.0	7.6	6.6
10061122-23122HLF	8.7	6.0	6.6	8.2	7.2
10061122-25122HLF	9.3	6.6	7.2	8.8	7.8

*For the corresponding position, please make an inquire to sales person in our company.

mat'l. code					surface ISO 1302 ✓		tolerance ISO 406 ISO 1101		projection 		product family 587F (YLL-D)			CODE JP					
ltr	description	ecn no	dr	date	tolerances unless otherwise specified								title 0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE						
A	Released	J10-0185	T.I	2010-07-06	angles	linear	± 0.2												
B	Revised	ELX-J-12415	T.I	2012-08-31															
C	Revised	ELX-J-20618	T.I	2015-04-17			± 2°												
					dr	T.SHISHITA		2015-04-17			dwg no 10061122						sheet of 5of7		size A3
					enrg														
					chr	M.Minato		2015-04-17											
					appd	N.Sasame		2015-04-17											
sheet index	revision sheet											type			Product Customer		Drawing		Rev. C

PRODUCT NO

10061122-**-142HLF



FPC

PARTS NAME	MATERIAL	QTY	REMARKS
6 BASE FILM	POLYAMDE	1	
7 CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4~12μm, Au 0.05~0.15μm
8 OVERLAY	POLYAMIDE	1	
9 STIFFENER	POLYAMIDE	1	

n:NO OF CONTACT

P/N	A	B	C	D	E
10061122-33142HLF	11.7	9.0	9.6	11.2	10.2
10061122-39142HLF	13.5	10.8	11.4	13.0	12.0
10061122-41142HLF	14.1	11.4	12.0	13.6	12.6
10061122-43142HLF	14.7	12.0	12.6	14.2	13.2
10061122-45142HLF	15.3	12.6	13.2	14.8	13.8
10061122-51142HLF	17.1	14.4	15.0	16.6	15.6

*For the corresponding position, please make an inquire to sales person in our company.

PARTS NAME	MATERIAL	QTY	REMARKS
1 HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2 ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3 CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA:Au SOLDER TAIL AREA:Au
4 CONTACT B	COPPER ALLOY	(n+1)/2	
5 FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni,Sn

n:NO OF CONTACT

NOTE
1.CO-PLANARITY:0.08mmMAX
2.THICKNESS OF A METAL MASK:0.1mm
3.FPC

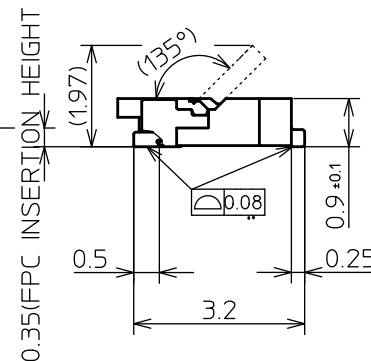
Adhesive method of supporting tape shall be heat crimping method
and thermosetting adhesive material shall be used.

4.PRODUCT

Recommended PCB layout and FPC area the same as 10064555-**-2110*LF(YLL-Upper contact type)

5.OTHER

This product meets European Union Directives and other country regulation
as described in GS-22-008



0.35(FPC) INSERTION HEIGHT

mat'l. code	surface	tolerance	projection	product family	CODE
ISO 1302	ISO 406	ISO 1101	MM	587F (YLL-D)	JP
lir	description	ecn no	dr	date	tolerances unless otherwise specified
A	Released	J10-0185	T.I	2010-07-06	± 0.2
B	Revised	ELX-J-01245-1	T.I	2012-08-31	± 2'
C	Revised	ELX-J-14161-1	T.I	2013-03-05	± 2'
dr	T.I SHISHITA	2013-03-05	engr	H.Suzuki	2013-03-05
chr	N.Sasame	2013-03-05	appd	N.Sasame	2013-03-05
sheet	revision	sheet	sheet	sheet	sheet
index	sheet	sheet	sheet	sheet	sheet